

ABSTRACT

The present invention allows multiple IC devices to be placed on the same substrate within a single BGA package. The invention requires minimum distances to be kept between electrical connections of the IC devices to maintain the electrical isolation, so that the devices can be operated at different voltage differentials. Signals between the devices can be connected externally from the package to each other utilizing galvanic isolation techniques. The invention provides the flexibility of choice for the customers to use isolation or not between the devices and takes up less PC board space because only a single package is used on the board.